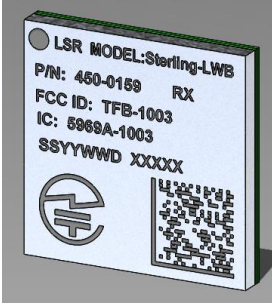




## ***DECLARATION OF CONFORMITY***

We, Laird Technologies  
W66 N220 Commerce Ct  
Cedarburg, WI. 53012 USA

This declaration is issued under the sole responsibility of the manufacturer:

Sterling-LWB is a high performance 2.4GHz WLAN (802.11 b/g/n –single stream n) and Bluetooth Smart Ready (BT 2.1+EDR, BT 3.0 and BT 4.1) combo module based on Broadcom’s BCM4343W.

	Part Number	Description
	450-0159 450-0159R 450-0159C	Sterling-LWB SIP Module Sterling-LWB SIP Module, Tape & Reel Sterling-LWB SIP Module, Cut Tape
	450-0148 450-0148R 450-0148C	Sterling-LWB Module, U.FL Sterling-LWB Module, U.FL Tape & Reel Sterling-LWB Module, U.FL Cut Tape
	450-0152 450-0152R 450-0152C	Sterling-LWB Module, Chip Antenna Sterling-LWB Module, Chip Antenna Tape & Reel Sterling-LWB Module, Chip Antenna Cut Tape

To which this declaration relates, is in compliance with all the applicable essential requirements, and other provisions of the Union Harmonization Legislation:

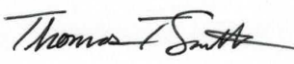
2014/53/EU	Radio Equipment Directive (RED)
2011/65/EU	RoHS Directive (See Appendix A for RoHS Exemptions)

Product compliance has been demonstrated on the basis of:

EN 60950-1:2006 +A11:2009 +A1:2010 +A12:2011 +A2:2013	For article 3.1a: Health and Safety
EN 62479:2010 EN 62311:2008	For article 3.1a: RF Exposure
EN 301 489-1 v2.1.1 (2017-02) EN 301 489-17 v3.1.1 (2017-02)	For article 3.1b: Electromagnetic Compatibility (EMC)
EN 300 328 v2.1.1 (2016-11)	For article 3.2: Effective use of spectrum allocated
EN 50581:2012	RoHS

The technical construction file is kept available at:

Laird Technologies  
W66 N220 Commerce Ct  
Cedarburg, WI. 53012  
USA  
Phone: (262) 375-4400

Issued on	June 12 <sup>th</sup> , 2017
Company name	Laird Technologies (formerly LSR)
Signature	
Printed name	Thomas T. Smith
Title	Director of EMC Compliance



**Appendix A RoHS Exemptions**

Component Type	EU RoHS Exemption Applied	
Resistor	7(c)-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound